LEAD FRAME AND PRODUCTION METHOD THEREOF, AND SEMICONDUCTOR DEVICE AND FABRICATION METHOD THEREOF

ABSTRACT OF THE DISCLOSURE

A lead frame comprises: outer leads formed by a metal base member; first interconnection film portions formed by a metal plating layer, each of which is disposed inside the outer leads in such a manner as to be connected to an inner end of one principal plane of the corresponding one of the outer leads, and at least one second interconnection film portion formed by the metal plating layer, which is disposed inside the outer leads in such a manner as not to be connected to the outer leads; and an insulating film formed to cover planes, opposed to the outer leads, of the first and second interconnection film portions, thereby holding the first and second interconnection film portions; wherein planes, opposed to the insulating film, of the first and second interconnection film portions are taken as semiconductor element mounting planes. With this configuration, the lead frame allows a plurality of semiconductor elements to be mounted on one semiconductor device without increasing the number of assembling steps, while making the thickness of the semiconductor device thin, and reducing the reliability and the production yield.

Fig. 1E